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Lecture 48 Lithography: Resolution and Immersion

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Improving Lithography

- Every couple of years we need to improve resolution while keeping costs in control

90 nm → 65 nm → 45 nm → 32 nm → 22 nm

- How is this regular improvement in resolution accomplished?

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Improving Lithography

- The Rayleigh Resolution Equation

$$R = k_1 \frac{\lambda}{NA}$$

Use "Resolution Enhancement" Technologies to lower k_1

Lower the wavelength

Increase the Numerical Aperture

R = the smallest "half pitch" that can be printed (pitch = center-to-center distance of a repeating pattern, a measure of how closely features can be packed together)

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Lowering the Wavelength

- Wavelength is a property of the light source
 - Early tools used lamps with 436-nm wavelength
 - Today's tools use 193-nm excimer lasers
- Lowering wavelength is hard
 - New light source
 - New lens materials
 - New photoresist
- The transition to the next wavelength (13.5 nm, Extreme Ultraviolet, EUV) is way behind schedule (and may never happen)

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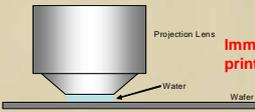
Lowering the "k₁" Factor

- The "k₁" factor is a collection of everything else that can be done to improve resolution
 - Improve the photoresist
 - Use "resolution enhancement" technologies like phase-shifting masks and off-axis illumination (fancy optical "tricks")
- The physical limit for k₁ is 0.25 (the lowest we can go, using 2-beam imaging)
 - Early processes had k₁ = 1.0
 - Today's best processes have k₁ = 0.28

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Increasing the Numerical Aperture (NA)

- Numerical Aperture is a property of the lens – how much light information can it capture?
 - Early tools had NA = 0.16
 - NA = n sin θ, the largest practical lens gives sin θ ≈ 0.93
- To increase NA beyond this, we must use immersion imaging (increase n)



Immersion Lithography: printing through water

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The Fluid Refractive Index

- At 193 nm, water has a refractive index of 1.436
 - Water can be made very pure, and has low absorption
- Adding water doesn't increase the NA, it allows an increased NA lens to be designed and built
- Spatial frequency: $f = n \sin \theta / \lambda$
- Rayleigh DOF for large angles (high NA):

$$DOF = \frac{k_2}{2} \frac{\lambda}{n(1 - \cos \theta)}$$

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Immersion DOF (same NA)

$$\frac{DOF(immersion)}{DOF(dry)} = \frac{1 - \sqrt{1 - (\lambda/p)^2}}{n - \sqrt{n^2 - (\lambda/p)^2}}$$

Pitch (nm)

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Immersion Conclusions

- For the same NA, immersion has DOF better than dry by a factor of at least the fluid index
- Thus, immersion enables better resolution without as big a drop in DOF as one would expect
- Of course, some practical issues had to be worked out...
 - Fluid flow during high-speed scanning
 - Bubbles, defects
 - Water interaction with photoresist

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Improving Resolution 1975 – 2010

	1975	2010	Improvement
Wavelength (nm)	436	193	2.3X
Numerical Aperture (NA)	0.16	1.35	8.4X
k_1 Factor	1.0	0.28	3.5X
Overall Resolution (nm)	2700	40	68X

How much further can resolution be improved?

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Hitting the Resolution Limit

- Wavelength is stuck at 193 nm, the highest NA we have is 1.35, and k_1 is limited to 0.25

$$R = k_1 \frac{\lambda}{NA} \geq 0.25 \frac{193nm}{1.35} = 36nm$$

- This resolution limit is technically the smallest "half pitch" that can be printed in a single pattern
 - Practical half-pitch limit is more like 38 – 40 nm
 - Minimum pitch is therefore 75 – 80 nm

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Lecture 48: What have we Learned?

- What are the three ways to improve resolution in optical lithography
- Which of those three ways has had the biggest impact on resolution over the years?
- What currently limits our ability to improve each of these three factors?
- What is the current resolution limit for single patterning?

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